

What is claimed is:

1 ✓ 1. A semiconductor manufacturing device having a mechanical  
2 drive part which is moved in a vacuum device while holding a  
3 substrate comprising,  
4 at least one discharge port for introducing inert gas into  
5 said vacuum device, and  
6 a flow rate control part for controlling the inert gas which  
7 is discharge into said vacuum device from said discharge port  
8 at a constant flow rate.

1 (2.) The semiconductor manufacturing device as claimed in claim  
2 1, further comprising an inspection processing part for  
3 inspecting said substrate.

1 ✓ 3. The semiconductor manufacturing device as claimed in claim  
2 1, further comprising an exposure processing part for exposing  
3 said substrate.

1 ✓ 4. The semiconductor manufacturing device as claimed in claim  
2 1, wherein said discharge port is disposed at a position in the  
3 vicinity of the substrate held by said mechanical drive part  
4 where it does not make contact with the substrate.

1 ✓ 5. The semiconductor manufacturing device as claimed in claim  
2 1, wherein said mechanical drive part is located between said  
3 discharge port and a vacuum exhaust port in said vacuum device.

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- 1 6. The semiconductor manufacturing device as claimed in claim  
2 1, wherein  
3 the total evacuation rate of the vacuum pump connected to said  
4 vacuum device is more than 300L/s and less than 5,000L/s,  
5 the degree of vacuum within said vacuum device is higher than  
6  $133 \times 10^{-7}$  kPa and lower than  $133 \times 10^{-4}$  kPa, and  
7 the flow rate of said inert gas is more than  $0.5 \text{ cm}^3/\text{min}$  and less  
8 than  $20 \text{ cm}^3/\text{min}$ .

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